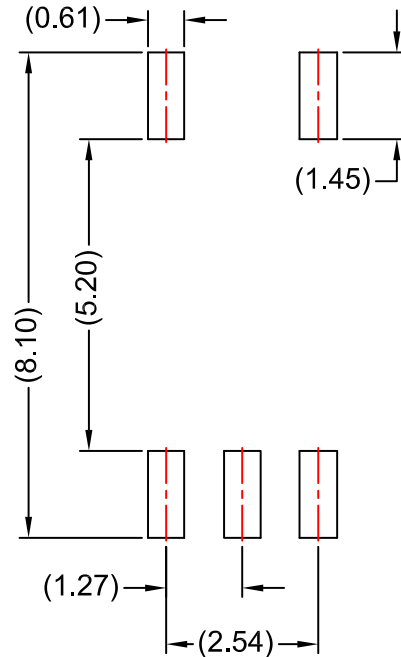
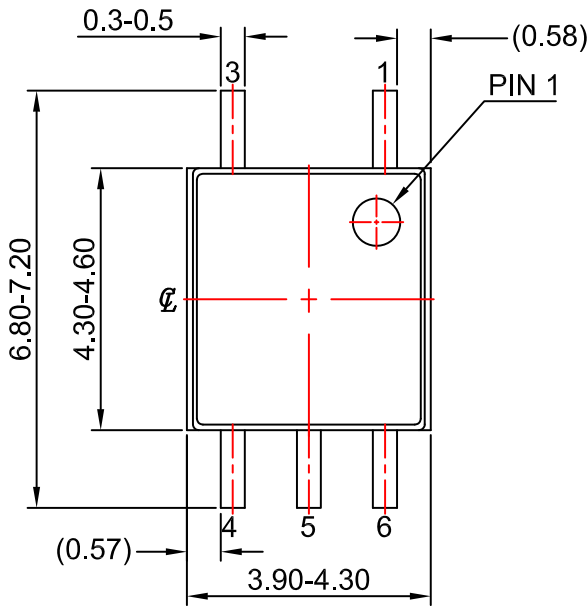


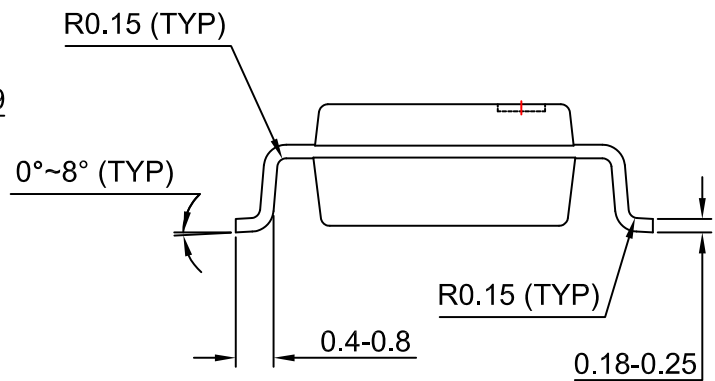
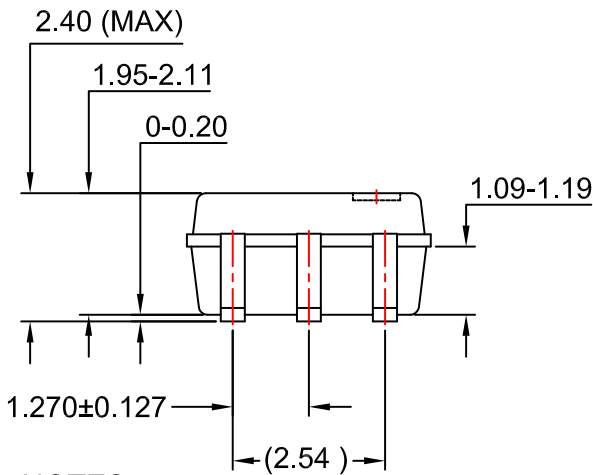
**MECHANICAL CASE OUTLINE**  
**PACKAGE DIMENSIONS**

MFP5 4.1X4.4, 2.54P  
CASE 100AM  
ISSUE 0

DATE 31 AUG 2016



**LAND PATTERN RECOMMENDATION**



**NOTES:**

- A) NO STANDARD APPLIES TO THIS PACKAGE
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSION

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<b>STATUS:</b>	<b>ON SEMICONDUCTOR STANDARD</b>	
<b>NEW STANDARD:</b>		
<b>DESCRIPTION:</b>	<b>MFP5 4.1X4.4, 2.54P</b>	<b>PAGE 1 OF 2</b>

